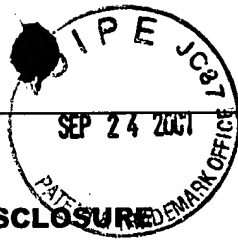


Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**
(use as many sheets as necessary)**COMPLETE IF KNOWN**

Application Number	09/887,767
Confirmation Number	9072
Filing Date	June 21, 2001
First Named Inventor	Whonchee Lee
Group Art Unit	3723
Examiner Name	

Sheet	1	of	1	Attorney Docket No.	108298515US2
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U.S. PATENT DOCUMENTS

EXAMINER INITIALS	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		NUMBER	Kind Code (if known)			
AS	AA	6,176,992		Talieh	1/23/01	class 1
AS	AB	5,930,699		Bhatia	7/27/99	1
AS	AC	5,807,165		Uzoh et al.	9/15/98	1 / 1001
	AD					
	AE					
	AF					
	AG					
	AH					
	AI					
	AJ					

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FOREIGN PATENT DOCUMENTS

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	AK							
	AL							
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	AN							
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OTHER PRIOR ART-NON PATENT LITERATURE DOCUMENTS

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AS	AP	SEILCHI KONDO, NORIYUKI SAKUMA, YOSHIO HOMMA, YASUSHI GOTO, NAOFUMI Ohashi, Hizuru Yamaguchi, and Nobuo Owada, "Abrasive-Free Polishing for Copper Damascene Interconnection", <i>Journal of the Electrochemical Society</i> , 147 (10) 3907-3913 (2000)	
AS	AQ		
	AR		

EXAMINER

DATE CONSIDERED

4/17/02

* EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).